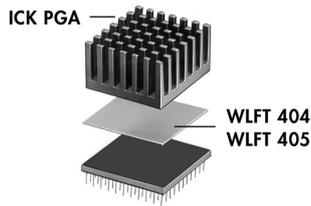


Data sheet Product ICK PGA 14 x 14



Heatsinks and active heatsinks for processors>Heatsinks for PGA
34,5 x 31,34 x 16,5 mm, for IC design PGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	34.5 mm
height:	16.51 mm
plate thickness:	5 mm
length:	31.34 mm
thermal resistance:	10 - 2.3 K/W
dissipation loss:	4.9 W
surface:	black anodised

Technical Drawing

